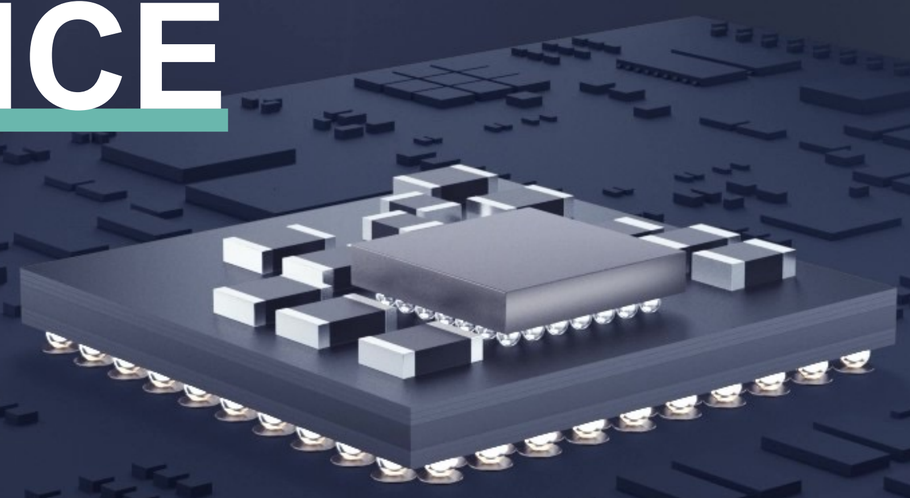
TEST AND REFERENCE BOARDS

Do it right the first time



Thank you for visiting the AT&S booth.
Visit ats.net for more information.

AT&S guarantees quality

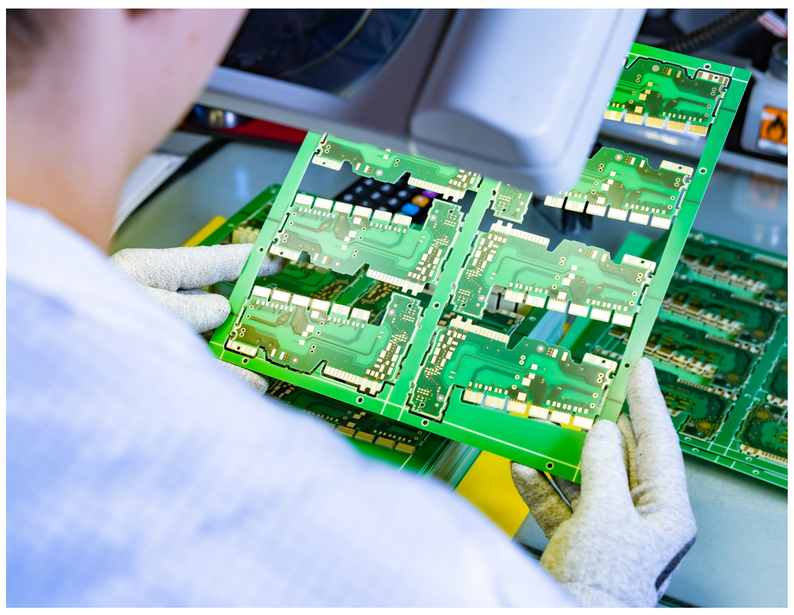
Quality control is a major concern in the semiconductor industry. The ultra-fine structures on modern microchips are expensive to develop and produce, and they're not particularly forgiving of mistakes. That's why processors and other chips are now routinely checked after production using IC testers. The chips are checked using test boards – complex adapters that make the fine structures of the microchips visible to the IC testers.

Experience is key

Due to the need to test its own products, AT&S has many years of experience with machines that test electronic systems. This expertise proves very useful when the company produces test boards and we're happy to share it with customers from the semiconductor industry. As one of the market leaders in high-end printed circuit boards, AT&S is also a top provider of reference boards.

At your fingertips

AT&S also offers its customers from the semiconductor industry the opportunity to produce their own reference boards. These display systems might be produced when a new generation of chips is developed, for instance. AT&S then produces reference boards that show how the new chip can be integrated onto a printed circuit board.



Product benefits at a glance

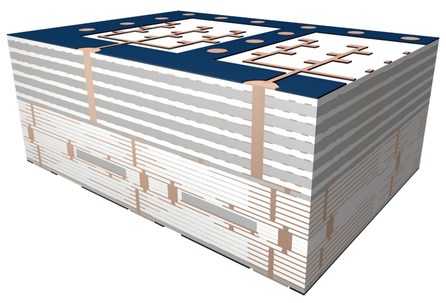
- Highly complex microchips can be checked on AT&S test boards.
- Due to the high number of layers, several simple chips can be checked at the same time.
- Reference boards save time and make it possible to develop the ecosystem for a chip at an early stage.

General design rule

	Standard	Advanced
Material	FR4 High Speed Materials: Meg6, Meg7, Tachyon 100G, Astra	
Layers	4L - 38L, up to 6-N-6	
Thickness	0.5mm - 3.2mm	0.5mm - 5mm
Max working panel size	21.3”x24.25”	21”x27”
LW/S	min 40µm/40µm @13µm cu	
Back drill	Yes	
Via size	min 0.15mm	
Aspect ratio	1:12	1:19
Fine pitch	0.4mm	0.3mm

Z-interconnect

Combining HDI, Baseboard and ECP



- Possible layer count and thickness amplification using ZiC
- Get access to HDI, mSAP and embedding capabilities